

# SEMICONDUCTOR AS A CATALYST FOR THE MALAYSIA ECONOMY



**NATIONAL E&E FORUM 2024**

MONDAY, 25 NOVEMBER 2024 | 8:30AM - 1:00PM

HILTON KUALA LUMPUR

## **MSIA NATIONAL E&E FORUM 2024**

Semiconductor As A Catalyst For The Malaysia Economy



The MSIA National E&E Forum 2024 is back and set to be a groundbreaking event for the semiconductor industry, bringing together experts, innovators, and enthusiasts from around the world. With a focus on cutting-edge technology and electronic components, this forum promises to be a hub for knowledge exchange and collaboration. Participants can expect engaging discussions, insightful presentations, and networking opportunities that will shape the future of the semiconductor field.

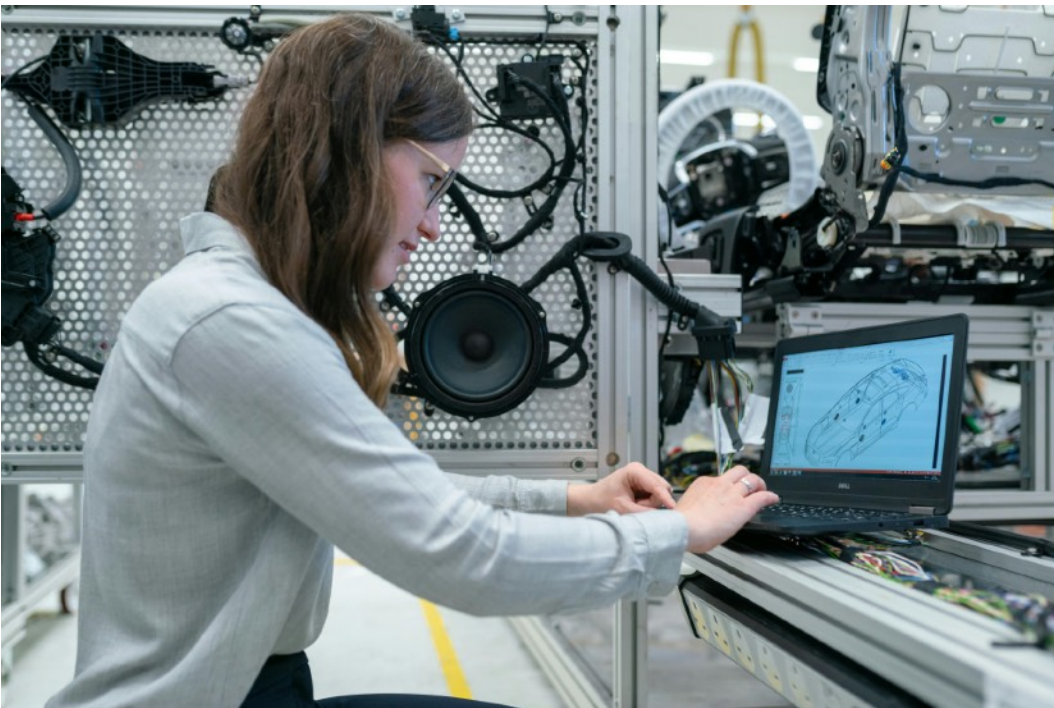
The National E&E Forum 2024 will provide a comprehensive exploration of the semiconductor industry's pivotal role in driving the Malaysia economy. Featuring keynote sessions and **three insightful panels**, the forum will bring together thought leaders and experts to address critical advancements and challenges shaping the industry.



## What To Expect

**Key topics** include strategies for advancing **IC design** with speakers from leading tech and semiconductor companies who will share real-world experiences and lessons on moving up the value chain. A panel on the transformative impact of **Artificial Intelligence**, featuring industry leaders in AI, cloud-computing, software and hardware, will delve into how AI is revolutionizing various sectors, reshaping industries, and raising questions about responsible innovation. Finally, experts will discuss the future of semiconductor manufacturing through **advanced packaging** technologies, revealing how these innovations support the continued scaling of Moore's Law and redefine manufacturing capabilities.

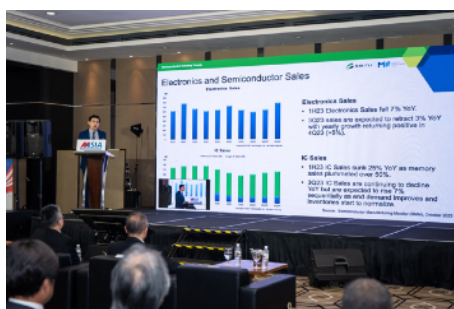
This forum offers attendees a deep dive into the technologies and strategies essential to the semiconductor sector's role as a catalyst for Malaysia economic transformation.



# Who will be attending

Semiconductor companies including

- MSIA Members
- SME Companies
- Startup Companies
- Existing players in Malaysia (Multi-Nationals, Malaysian)
- Hi-Tech Firms & Innovation Players
- Potential investors into Malaysia
- Service Providers (including Investment Analysts, Consultants, Banks)
- Foreign Chambers of Commerce
- Investment promotion Agencies
- Other relevant industry associations
- Government Agencies
- Press members



# Engaging Program

## Keynote Presentation

### The Future of IC Design - Trends, Challenges & Opportunities

Exploring how integrated circuit (IC) design is evolving to meet the demands of today's high-tech applications. The presentation will cover emerging trends, key design challenges, and unique opportunities for Malaysia's semiconductor sector, offering insights into how the industry can capitalize on these advancements to drive growth and innovation.

## Panel Discussion 1: IC Design

### Strategies to move up the value chain - areas of opportunities & lessons of success & failures

The discussion will delve into strategies for advancing within the integrated circuit (IC) design industry, pinpointing growth opportunities, and sharing real-world insights from both successful and challenging experiences. Panelists will discuss the evolving landscape of IC design and provide valuable perspectives on how companies can enhance competitiveness and drive innovation on a global scale.



# Engaging Program

## Panel Discussion 2: AI

### How is AI revolutionizing the world?

Industry experts will explore the transformative impact of artificial intelligence (AI) in various sectors. The panel will discuss innovative AI applications, the challenges of implementation, and the ethical considerations surrounding this technology. Attendees will gain insights into how AI is reshaping industries, driving efficiency, and creating new opportunities for businesses and society alike, while also addressing the future of work and the importance of responsible AI development.

## Panel Discussion 3: Advanced Packaging

### How AP will scale Moore's law & transform semiconductor manufacturing

In this forward-looking panel experts will examine how breakthroughs in advanced packaging are enabling the continued scaling of Moore's Law. Panelists will discuss innovative packaging techniques that enhance performance and efficiency, as well as their impact on semiconductor manufacturing. Gain insights into how these advancements are reshaping the production landscape, supporting the demand for powerful, compact technologies, and driving new possibilities for the future of the industry.



# The Venue

**Hilton Kuala Lumpur**  
Sentral Ballroom A & B,  
Hilton Kuala Lumpur  
3, Jalan Stesen Sentral,  
KL Sentral, 50470 KL



# Sponsorship Opportunities

Maximize your **company's visibility** and **strengthen brand equity** by sponsoring this event.

Sponsorship submission closes on Monday, 11 Nov 2024. For enquiries, contact [faz.adnan@msia.org.my](mailto:faz.adnan@msia.org.my)

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<b>Private Luncheon</b>	✓ 2 paxs	✓ 1 pax	✓ 1 pax
<b>Complimentary Tickets</b>	6 tickets	4 tickets	2 tickets
<b>Speaker / Moderator Slot</b> 1 session, subject to availability & suitability	✓	✓	
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Register or learn more at [events.msia.org.my/forum2024](https://events.msia.org.my/forum2024)





# NATIONAL E&E FORUM 2024

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For enquiries, you may contact :

Faz Adnan  
+60 12 621 6496  
[faz.adnan@msia.org.my](mailto:faz.adnan@msia.org.my)

